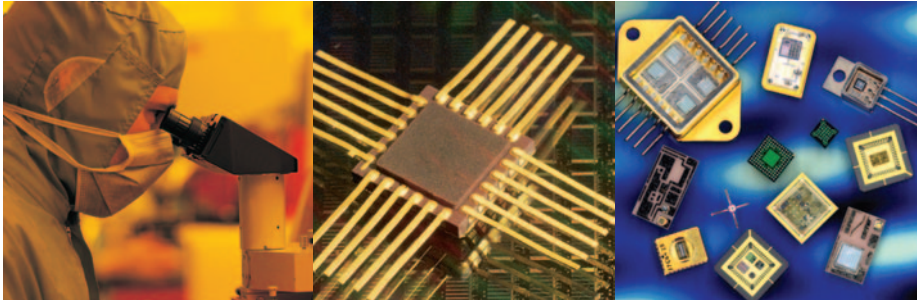


# Semiconductor Die Packaging, Test and Obsolescence Services for Aerospace Applications



MANUFACTURED  
PRODUCTS &  
SERVICES



**CURRENT APPLICATIONS  
SUPPORTED BY MICROSS  
COMPONENTS INCLUDE:**

- **ALTITUDE DETECTOR**
- **COCKPIT SPEECH  
RECOGNITION UNIT**
- **ENGINE CONTROL**
- **FUEL PUMP**
- **ACTUATOR CONTROL**
- **DE-ICER**
- **BRAKING SYSTEM**
- **GPS**





# Semiconductor Die Packaging, Test and Obsolescence Services for Aerospace Applications

## MARKETS

Long term experience of the aerospace marketplace. Also active in space, military and commercial markets.

## SEMICONDUCTOR PACKAGING

Europe's widest range of packaging capabilities. Ceramic, metal can or laminate (COB) packages.

## MINIATURISATION

High density packaging solutions including chip on board on laminate or flex, flip chip on board, mixed technology (SMA/COB) or standard SMA modules. High reliability solutions using ceramic substrates are also available.

## OBSOLESCENCE SOLUTIONS

Range of services including die banking, component replacement, footprint compatible solutions, adaptors and ASIC devices.

## ASIC DESIGN AND PACKAGING

Full service including in house ASIC design, probe, package design, packaging, test and qualification.

## TEST SERVICES/UPSCREENING

Analog, digital, power, memory and mixed signal test capability. Upscreen devices to military, JANTX/TXV or customer specification.

## CAPABILITY

Design, manufacture and test in-house. Many years experience of semiconductor die inspection, packaging and materials.

## QUALITY

Microcross components is an AS9100 approved manufacturing and test facility. Operating with industry standards used in Military, Space, Medical and Industrial markets.

## DELIVERY

Several customer information/delivery systems in place including KANBAN. Direct input to customer information/tracking systems, secure online information access.

## KEY SERVICES

- Semiconductor die packaging
- Ceramic and metal can packaging
- Chip on board to laminate or flex
- Medium volume plastic packaging
- Miniaturisation (System in Package)
- Obsolescence solutions
- Die banking
- ASIC design and packaging
- Test services
- Upscreening
- Anti-counterfeit services
- Upscreening to JANTX / JANTXV

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OUR MANUFACTURED PRODUCTS & SERVICES DIVISION OFFERS A WEALTH OF EXPERTISE IN DESIGN, PROCESSING AND PRODUCTION OF SEMICONDUCTORS, CONNECTORS AND OTHER ELECTRO-MECHANICAL COMPONENTS WITH THE HIGHEST DEGREE OF QUALITY, HI-RELIABILITY AND PERFORMANCE.



For further information visit [www.microcross.com](http://www.microcross.com)